

P3 (Power-Performance-Process) Optimization of Nano-CMOS SRAM using Statistical DOE-ILP

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Summary and Conclusions

- ❖ A novel design flow is presented for simultaneous P3 (power minimization, performance maximization and process variation tolerance) optimization of nano-CMOS circuits.
- ❖ For demonstration of the effectiveness of the flow, a 45 nm single-ended 7-transistor SRAM is used as example circuit.
- ❖ The SRAM cell is subjected to a dual- V_{Th} assignment based on a novel statistical Design of Experiments-Integer Linear Programming (DOE-ILP) approach.
- ❖ Experimental results show 44.2% power reduction (including leakage) and 43.9% increase in the read static noise margin compared to the baseline design.
- ❖ The process variation analysis of the optimized cell is carried out considering the variability in 12 parameters.

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Abstract

- In this research paper, a novel design flow is presented for simultaneous P3 (power minimization, performance maximization and process variation tolerance) optimization of nano-CMOS circuits.
- The SRAM cell is subjected to a dual-V_{Th} assignment based on a novel statistical Design of Experiments-Integer Linear Programming (DOE-ILP) approach.
- A 45nm single-ended 7-transistor SRAM is used as example circuit.
- Experimental results show 44.2% power reduction (including leakage) and 43.9% increase in the read static noise margin compared to the baseline design.
- The process variation analysis of the optimized cell is carried out considering the variability effect in 12 device parameters.

Introduction, Motivation, and Contributions

- In case of nanoscale circuit maintaining power, performance and process variation simultaneously becomes a major design challenge.
- Different design methods have been proposed like decrease in supply voltage, which reduces the dynamic power quadratic ally and reduces the leakage power linearly. However, substantial problems have been noted when the traditional six-transistor.
- SRAM cell is subjected to ultra-low voltage supply as it gives poor stability. In this paper a well-established process-level technique, called dual-V_{Th} (threshold voltage) is used for reduction of power consumption.
- Read static noise margin (SNM) is defined as the minimum DC noise voltage which is required to flip the state of the SRAM cell during the read operation. The “read SNM” here is treated as a measure of performance.

The Proposed Methodology for P3 Optimality

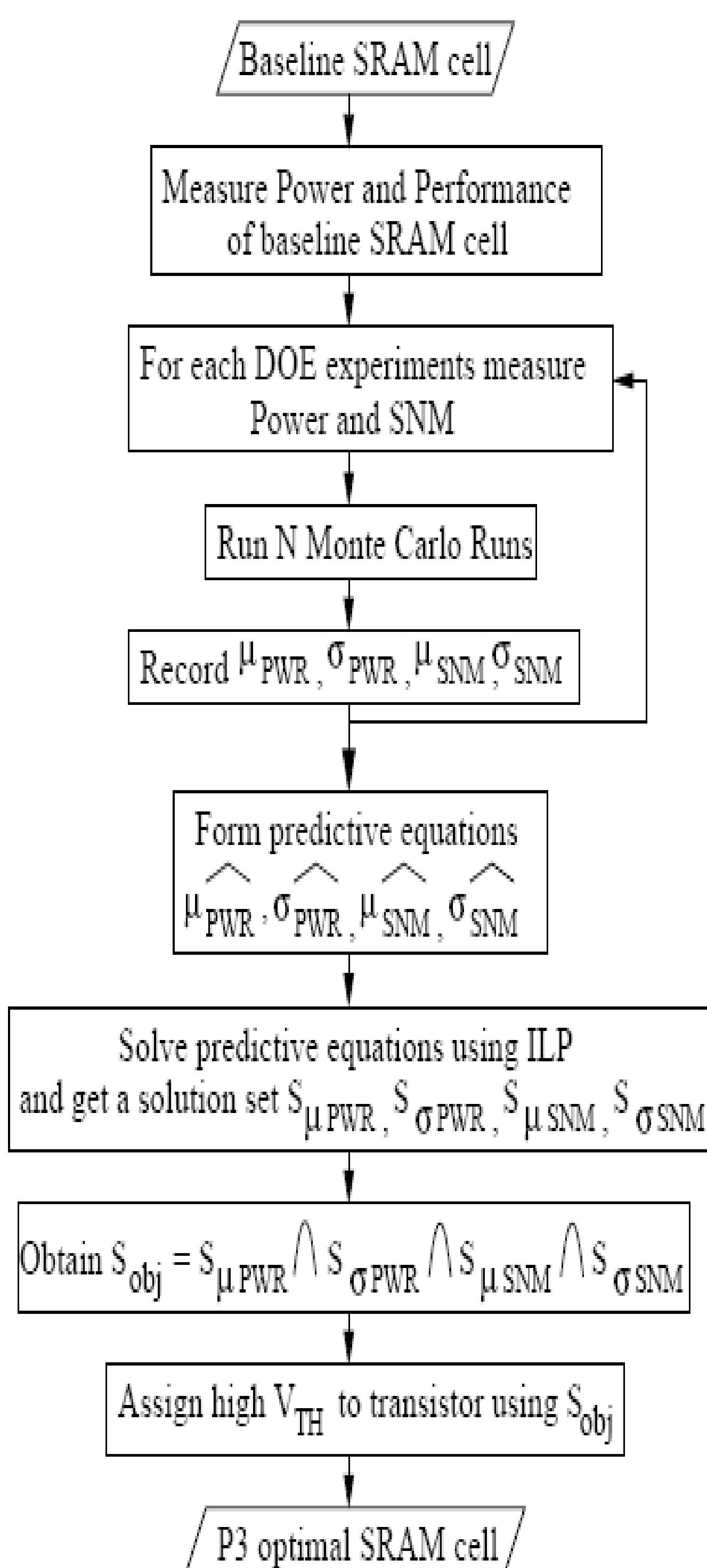


Figure 1. Proposed flow for P3-Optimal SRAM.

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VLSI Design and CAD Laboratory (VDCL)

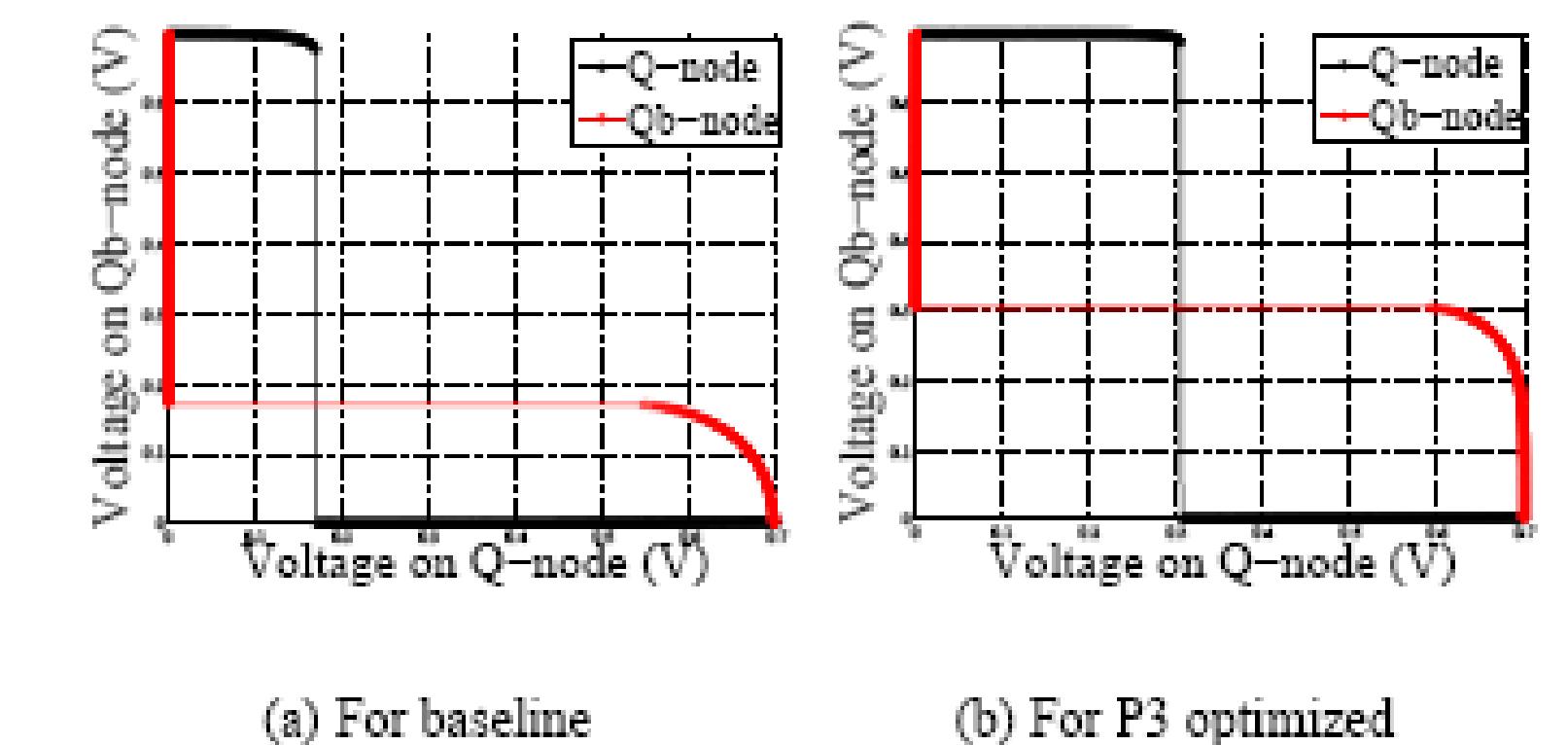


Figure 9. Butterfly curves of the SRAM.

The optimized butterfly curve is shown in Fig. 9(b)

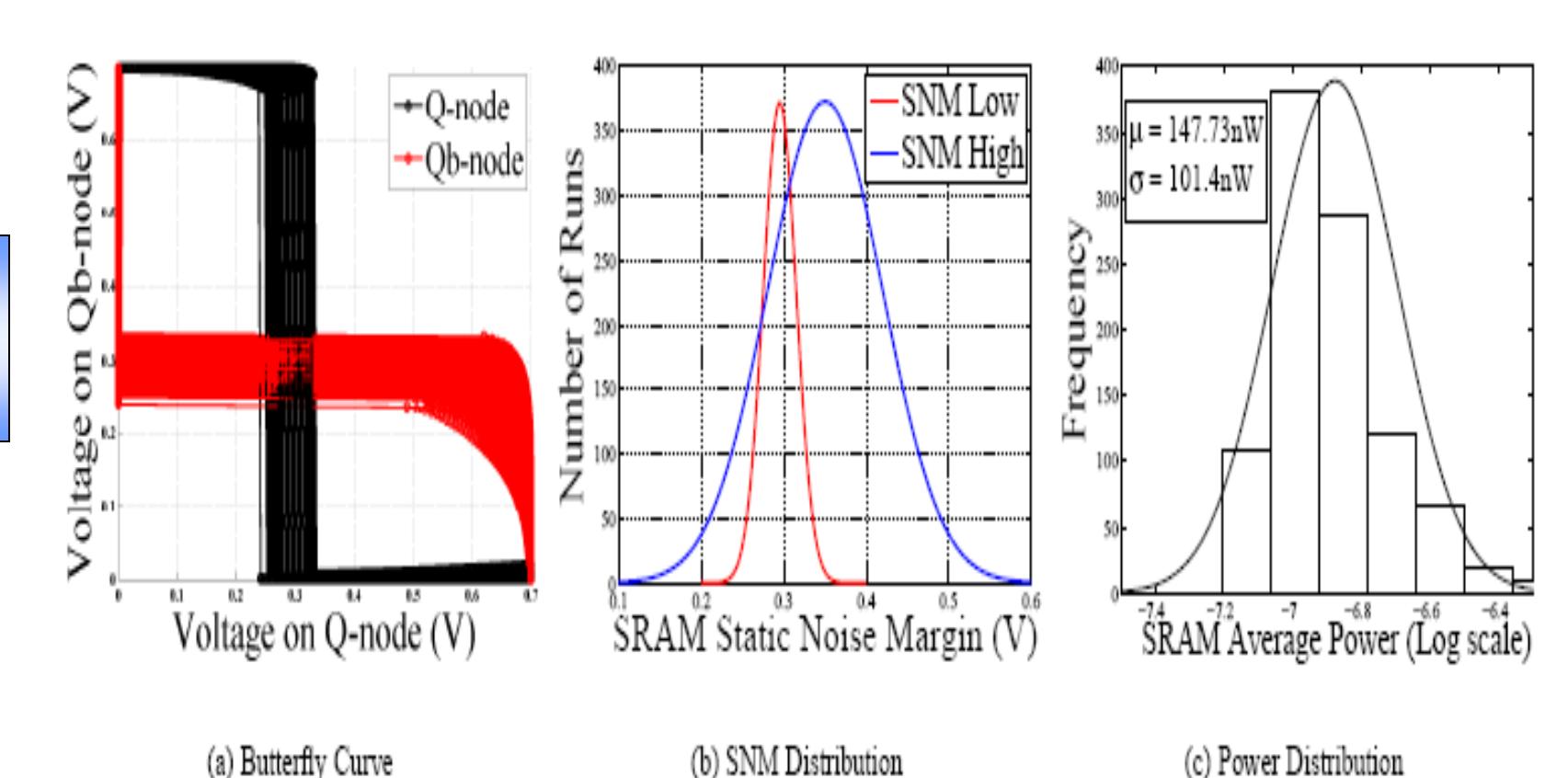


Fig. (a) shows the effect of process variations on the butterfly curve of the P3 optimized SRAM. Fig. (b) shows the distributions for “SNM High” and “SNM Low” extracted from the Monte Carlo simulations. “SNM Low” is treated as the actual SNM. Fig. (c) shows the distribution of average power of the P3 optimized SRAM cell under process variations.

Summary, Conclusions, and Future Works

- A statistical DOE-ILP approach has been presented in this paper for simultaneous P3 optimization of SRAM cell.
- As part of extension of this research, a P4 optimal methodology is under consideration, where the 4th “P” would be parasitics. Thermal effects will also be incorporated in the future which will lead to what is envisioned as P4VT optimal; V stands for voltage and T stand for temperature.
- Also, array-level optimization of SRAM with mismatch and process variation will be considered as part of the design flow.

Optimization	Parameter	Value	Change
S _{obj}	Average power P _{SRAM}	113.6 nW	44.2%
S _{obj}	SNM	303.3 mV	43.9%

